

Docket No.: M4065.0222/P222-B
(PATENT)

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Design Application of:
Tongbi Jiang, et al.

Application No.: (Divisional application of Ser.
No.09/680,473 under rule 53(b))

Group Art Unit: 3729

Filed: Concurrently herewith

Examiner: Paul D. Kim

For: METHOD OF MAKING A CENTER BOND
FLIP CHIP SEMICONDUCTOR CARRIER
(as amended)

Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

PRELIMINARY AMENDMENT

Dear Sir:

Prior to examination on the merits, please amend the above-identified U.S.
patent application as follows:

Amendments to the Specification begin on page 2 of this paper.

Amendments to the Claims are reflected in the listing of claims beginning on page 3 of
this paper.